

<b>STN</b>	<b>Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy</b> <b>Časť 2-501: Skúšobné metódy na materiály na spájacie štruktúry</b> <b>Meranie pružnosti a retenčný faktor odolnosti pružných dielektrických materiálov</b>	<b>STN EN IEC 61189-2-501</b>  34 6513
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-501: Test methods for materials for interconnection structures - Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/22

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EUROPEAN STANDARD

**EN IEC 61189-2-501**

NORME EUROPÉENNE

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**Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-501: Test methods for materials for interconnection structures - Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials (IEC 61189-2-501:2022)**

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-501: Méthodes d'essai des matériaux pour structures d'interconnexion - Mesure de la puissance élastique et du facteur de rétention de la puissance élastique des matériaux diélectriques flexibles (IEC 61189-2-501:2022)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-501: Prüfverfahren für Materialien für Verbindungsstrukturen - Messung der Belastbarkeit und Belastbarkeit Rückhaltefaktor flexibler dielektrischer Materialien (IEC 61189-2-501:2022)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
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**EN IEC 61189-2-501:2022 (E)****European foreword**

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IEC 61189-2-501

Edition 1.0 2022-02

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –  
Part 2-501: Test methods for materials for interconnection structures –  
Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials**

**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –  
Partie 2-501: Méthodes d'essai des matériaux pour structures d'interconnexion –  
Mesure de la puissance élastique et du facteur de rétention de la puissance élastique des matériaux diélectriques flexibles**



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IEC 61189-2-501

Edition 1.0 2022-02

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS  
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-501: Test methods for materials for interconnection structures –  
Measurement of resilience strength and resilience strength retention  
factor of flexible dielectric materials**

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Draft	Report on voting
91/1765/FDIS	91/1774/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.



This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

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## **TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –**

### **Part 2-501: Test methods for materials for interconnection structures – Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials**

#### **1 Scope**

This part of IEC 61189 establishes a method suitable for testing the softness of FCCL (Flexible Copper Clad Laminate) products and related materials. This method determines the resilience under specified conditions. The test is performed on the sample as manufactured and without conditioning. The test does not apply to the resilience force lower than 10 mN.

#### **2 Normative references**

There are no normative references in this document.

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